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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V_{GSS}	±8	V
Continuous Drain Current (Note 6) V_{GS} = 4.5V	Steady State	T_A = +25°C	I_D	6.2	A
Maximum Body Diode Forward Current (Note 6)			I_S	1.5	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	40	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{\theta JA}$	105	°C/W
	t<10s		76	
Total Power Dissipation (Note 6)	T_A = +25°C	P_D	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	76	°C/W
	t<10s		50	
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	15	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 16V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	0.4	—	1.5	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	20	24	mΩ	V_{GS} = 4.5V, I_D = 6.2A
		—	24	32		V_{GS} = 2.5V, I_D = 5.2A
Diode Forward Voltage	V_{SD}	—	—	1.2	V	V_{GS} = 0V, I_S = 1.3A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	856	—	pF	V_{DS} = 10V, V_{GS} = 0V f = 1.0MHz
Output Capacitance	C_{oss}	—	83	—		
Reverse Transfer Capacitance	C_{rss}	—	78	—		
Total Gate Charge	Q_g	—	8.3	—	nC	V_{GS} = 4.5V, V_{DS} = 10V, I_D = 6.2A
Gate-Source Charge	Q_{gs}	—	1.3	—		
Gate-Drain Charge	Q_{gd}	—	3.1	—		
Turn-On Delay Time	$t_{D(ON)}$	—	13.2	—	ns	V_{DD} = 10V, V_{GS} = 4.5V, I_D = 1A, R_G = 6Ω
Turn-On Rise Time	t_R	—	12.6	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	65	—		
Turn-Off Fall Time	t_F	—	22	—		

Notes:
5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to production testing.

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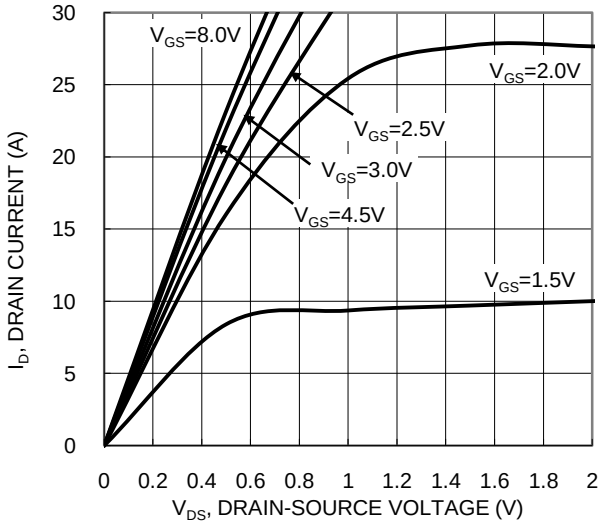

Figure 1. Typical Output Characteristic

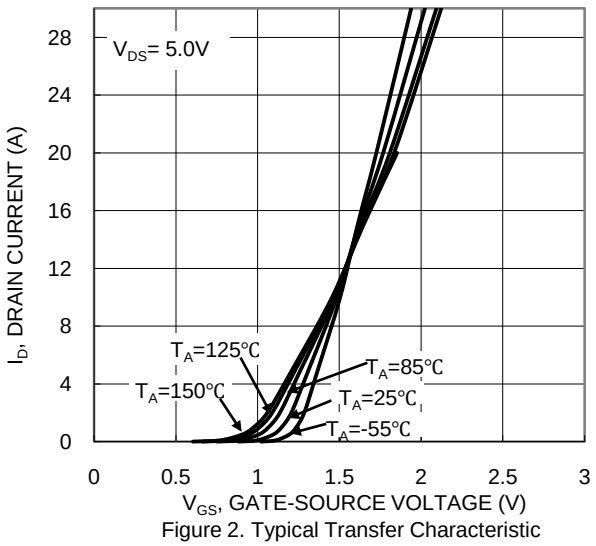

Figure 2. Typical Transfer Characteristic

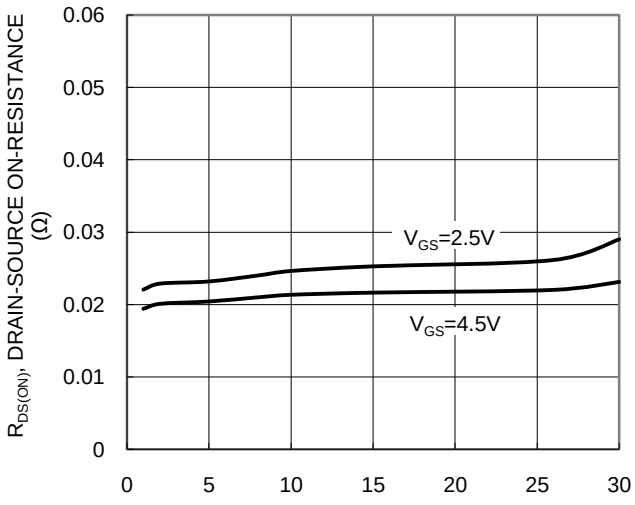

Figure 3. Typical On-Resistance vs. Drain Current

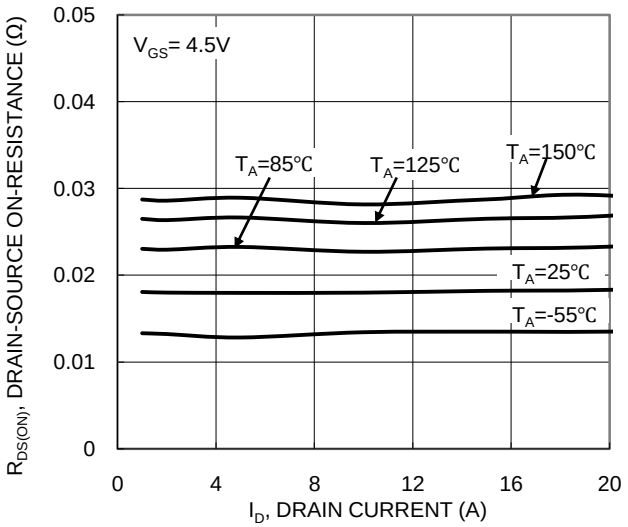

Figure 4. Typical On-Resistance vs. Drain Current and Temperature

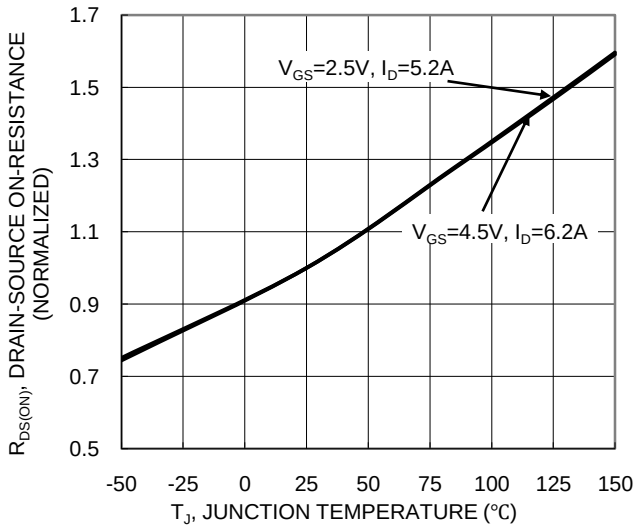

Figure 5. On-Resistance Variation with Temperature

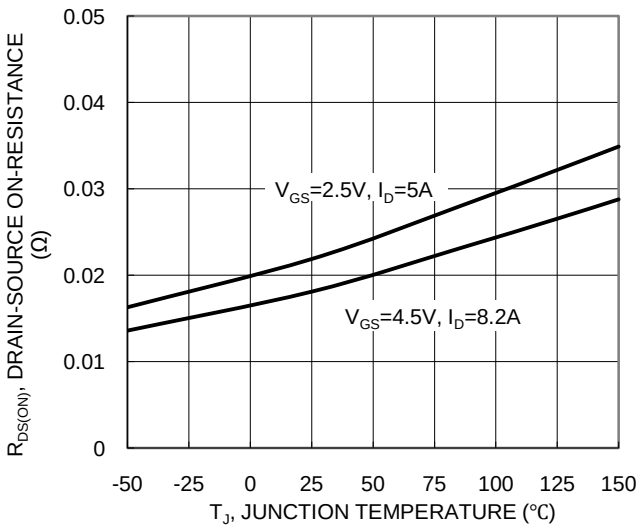

Figure 6. On-Resistance Variation with Temperature

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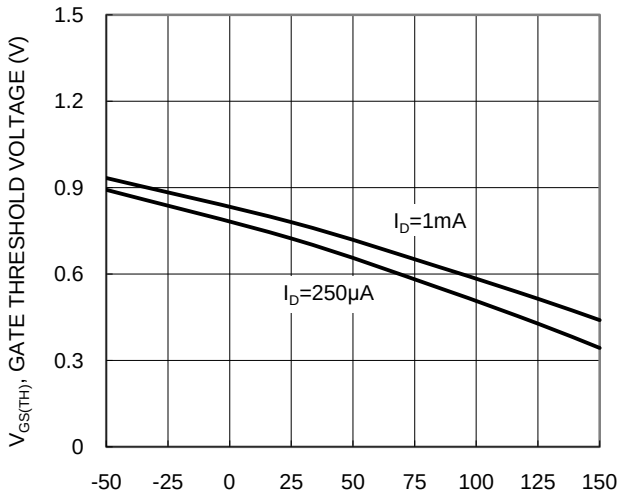

Figure 7. Gate Threshold Variation vs. Temperature

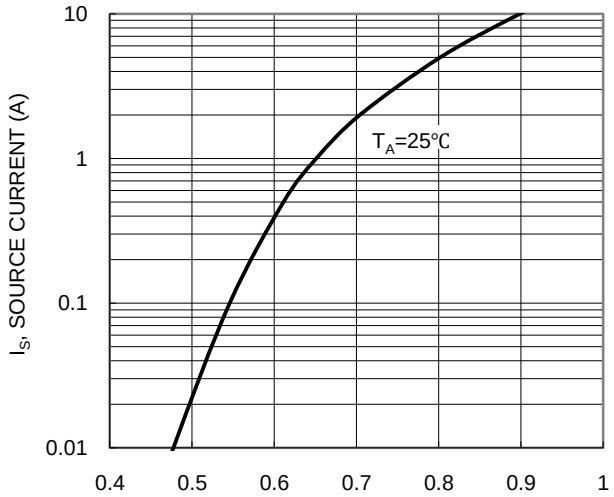

Figure 8. Diode Forward Voltage vs. Current

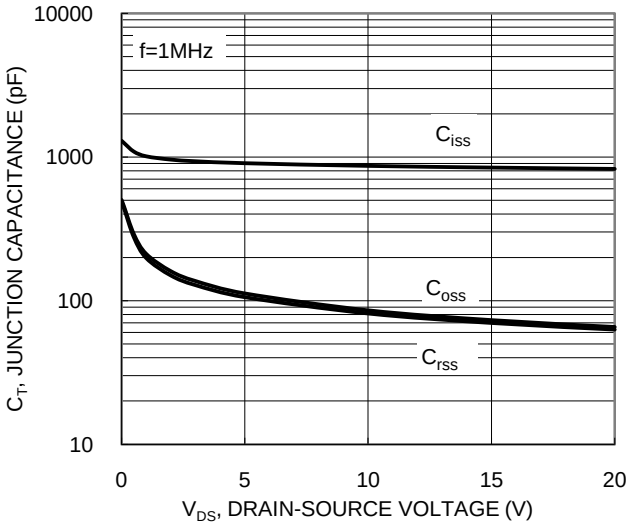

Figure 9. Typical Junction Capacitance

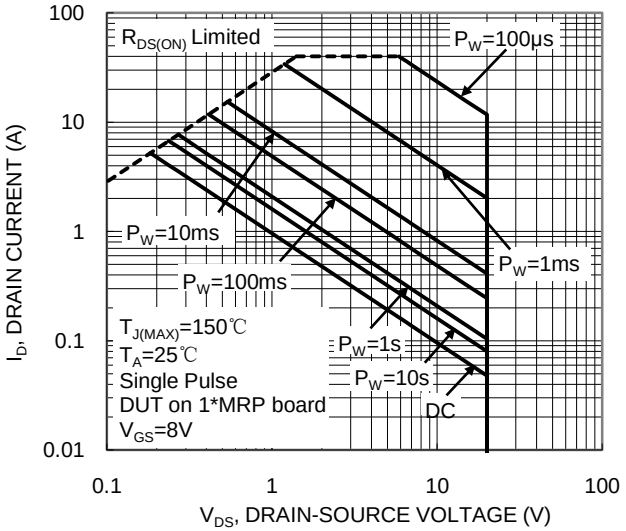

Figure 10. SOA, Safe Operation Area

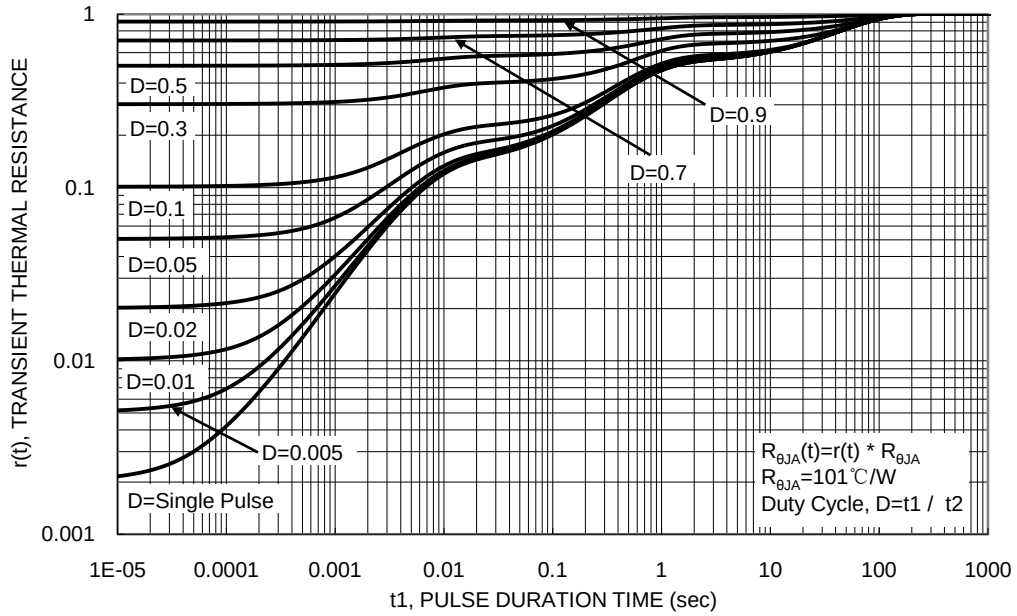

Figure 11. Transient Thermal Resistance

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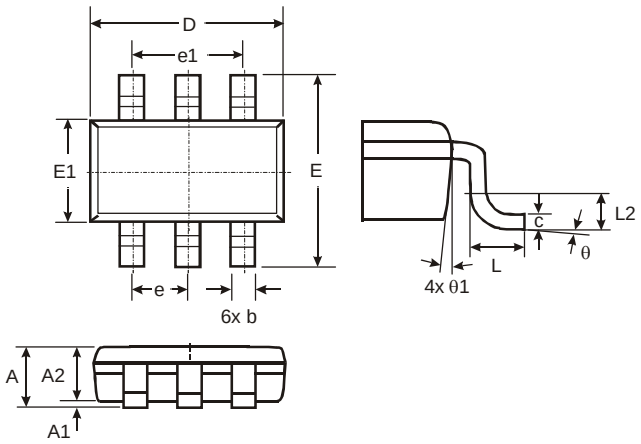
Package Outline Dimensions

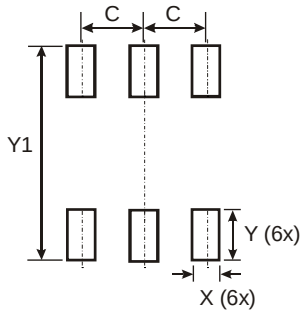
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



TSOT26			
Dim	**Min**	**Max**	**Typ**
A	—	1.00	—
A1	0.01	0.10	—
A2	0.84	0.90	—
D	—	—	2.90
E	—	—	2.80
E1	—	—	1.60
b	0.30	0.45	—
c	0.12	0.20	—
e	—	—	0.95
e1	—	—	1.90
L	0.30	0.50	—
L2	—	—	0.25
θ	0°	8°	4°
θ1	4°	12°	—
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199

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